

PART INFORMATION

Mfg Item Number	MAC7131MVF40R2
Mfg Item Name	MAPBGA 208 17*17*0.8P1.0

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2018-05-19
Response Document ID	5253K00090D179A1.50
Contact Name	Freescale Semiconductor Inc
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DECLARATION

EU RoHS	No
Pb Free	No
HalogenFree	Yes
Plating Indicator	e0
EU RoHS Exemption(s)	

MANUFACTURING

Mfg Item Number	MAC7131MVF40R2
Mfg Item Name	MAPBGA 208 17*17*0.8P1.0
Version	ALL
Weight	0.861400
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	240 C
Max Time at Peak Temperature	30 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Non-Conductive Epoxy/Adhesive	0.0027						g				
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.0002025	g	75000	7.5	235	0.0235
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Crosslinked acrylate polymer	25767-43-5		0.00054	g	200000	20	626	0.0626
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Other polymers	-		0.0002025	g	75000	7.5	235	0.0235
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other polymers	-		0.00054	g	200000	20	626	0.0626
Non-Conductive Epoxy/Adhesive		Glass	Silica, vitreous	60676-86-0		0.001215	g	450000	45	1410	0.141
Solder Balls - Low Lead	0.2028						g				
Solder Balls - Low Lead		Lead/Lead Compounds	Lead	7439-92-1		0.073008	g	360000	36	84755	8.4755
Solder Balls - Low Lead		Metals	Silver, metal	7440-22-4		0.004056	g	20000	2	4708	0.4708
Solder Balls - Low Lead		Metals	Tin, metal	7440-31-5		0.125736	g	620000	62	145967	14.5967
Silicon Semiconductor Die	0.04						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.0008	g	20000	2	928	0.0928
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.0392	g	980000	98	45507	4.5507
Die Encapsulant, Halogen-free	0.4784						g				
Die Encapsulant, Halogen-free		Metals	Other aluminum compounds	-		0.014352	g	30000	3	16661	1.6661
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.004784	g	10000	1	5553	0.5553
Die Encapsulant, Halogen-free		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4		0.014352	g	30000	3	16661	1.6661
Die Encapsulant, Halogen-free		Plastics/polymers	Other phenolic resins	-		0.014352	g	30000	3	16661	1.6661
Die Encapsulant, Halogen-free		Glass	Silica, vitreous	60676-86-0		0.40664	g	850000	85	472081	47.2081
Die Encapsulant, Halogen-free		Plastics/polymers	Other Non-halogenated Epoxy resins	-		0.02392	g	50000	5	27768	2.7768
Organic Substrate, Halogen-free	0.1313						g				
Organic Substrate, Halogen-free		Metals	Barium sulfate	7727-43-7		0.00920754	g	70126	7.0126	10689	1.0689
Organic Substrate, Halogen-free		Metals	Copper, metal	7440-50-8		0.03389287	g	258133	25.8133	39346	3.9346
Organic Substrate, Halogen-free		Plastics/polymers	Epikote 862	28064-14-4		0.01008095	g	76778	7.6778	11702	1.1702
Organic Substrate, Halogen-free		Plastics/polymers	Formaldehyde, polymer with 2-methylphenol, glycidyl ether	64425-89-4		0.01426522	g	108646	10.8646	16560	1.656
Organic Substrate, Halogen-free		Metals	Gold, metal	7440-57-5		0.00042528	g	3239	0.3239	493	0.0493
Organic Substrate, Halogen-free		Nickel (external applications only)	Nickel	7440-02-0		0.0032189	g	25300	2.53	3856	0.3856
Organic Substrate, Halogen-free		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4		0.0050488	g	41926	4.1926	6390	0.639
Organic Substrate, Halogen-free		Glass	Fibrous-glass-wool	65997-17-3		0.03371784	g	256800	25.68	39143	3.9143
Organic Substrate, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.00289018	g	22012	2.2012	3355	0.3355
Organic Substrate, Halogen-free		Solvents, additives, and other materials	Other Aromatic carbonyl compounds	-		0.00142844	g	11280	1.128	1716	0.1716
Organic Substrate, Halogen-free		Metals	Aluminum Hydroxide	21645-51-2		0.01651491	g	125780	12.578	19172	1.9172
Bonding Wire, PdCu	0.0062						g				
Bonding Wire, PdCu		Metals	Copper, metal	7440-50-8		0.0060822	g	981000	98.1	7050	0.705
Bonding Wire, PdCu		Metals	Gold, metal	7440-57-5		0.0000962	g	1000	0.1	7	0.0007
Bonding Wire, PdCu		Metals	Palladium, metal	7440-05-3		0.0001116	g	18000	1.8	129	0.0129

LINKS

MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcdfs/MAC7131MVF40R2_IPC1752_v11.xml

http://www.freescale.com/mcdfs/MAC7131MVF40R2_IPC1752A.xml